

# 25 nm InP HEMT LNAs and Receiver Technology for the TWICE Instrument

THE VALUE OF PERFORMANCE.  
**NORTHROP GRUMMAN**

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Presented by Bill Deal

William R. Deal, Pekka Kangaslahti\*, Alex Zamora, Erich Schlecht\*,  
Kevin Leong, Gerry Mei, Sean Shih, and Steven C. Reising\*\*

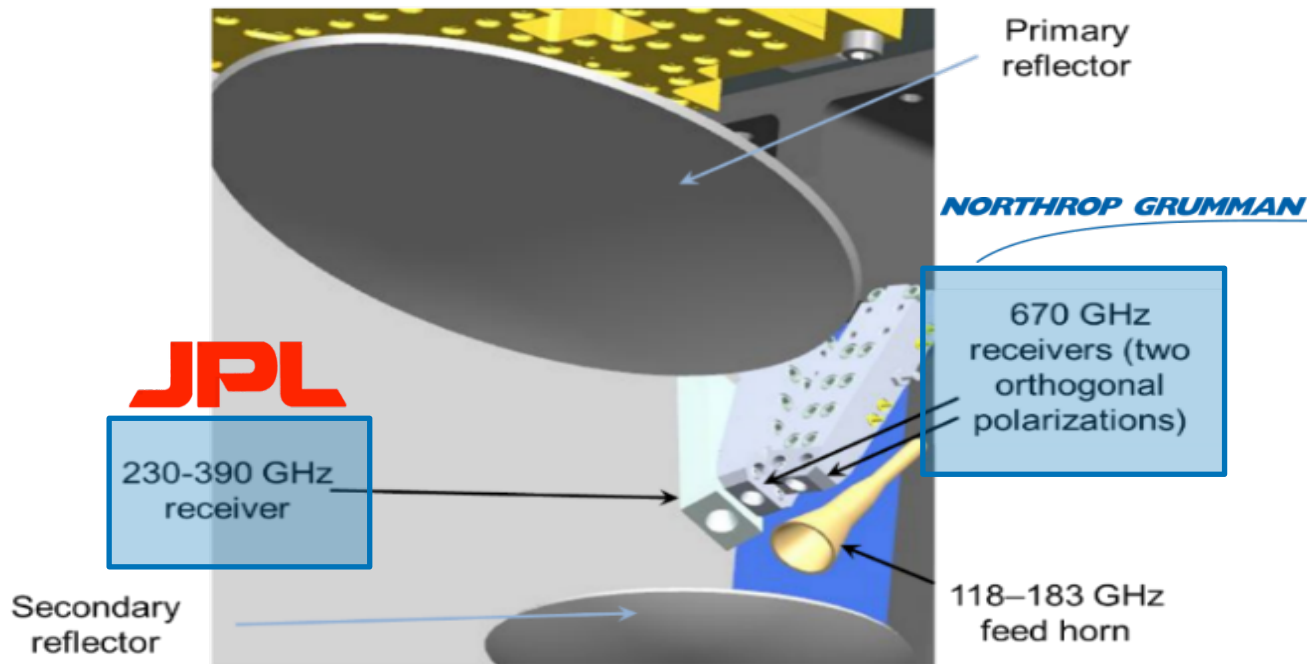
Northrop Grumman, Jet Propulsion Laboratory\*  
and Colorado State University\*\*



- Outline
- Motivation
- 670 GHz Receiver Update
- 230-390 GHz Update
- Conclusion

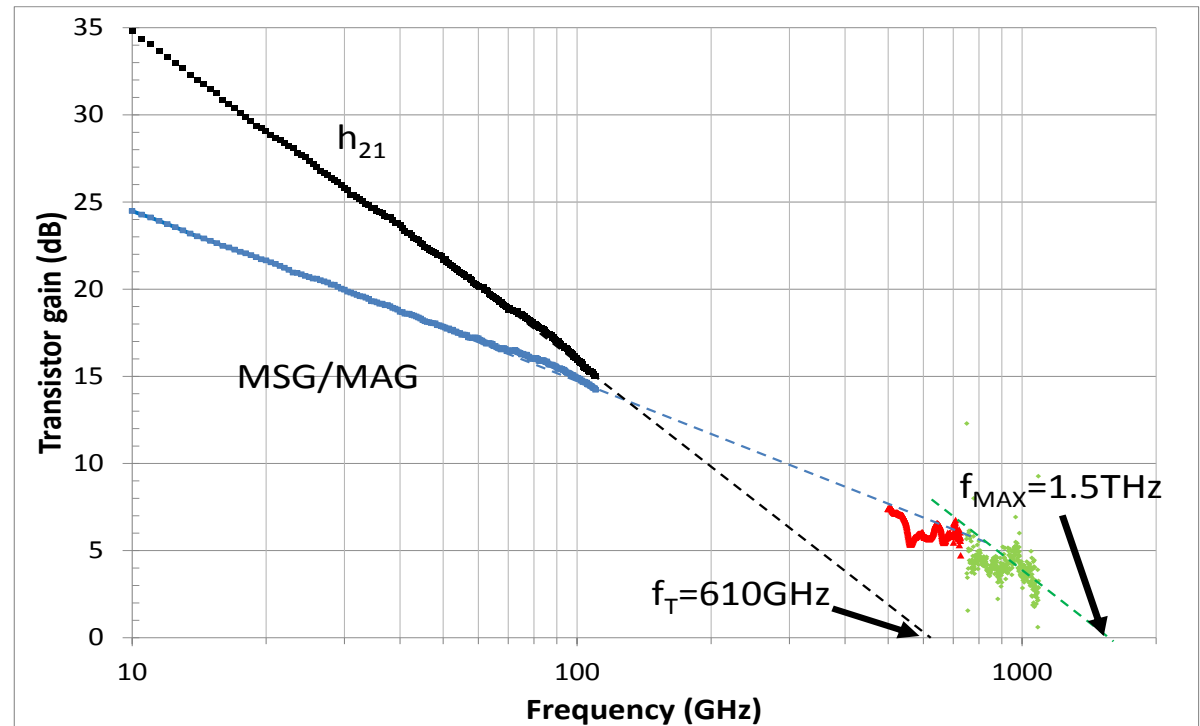
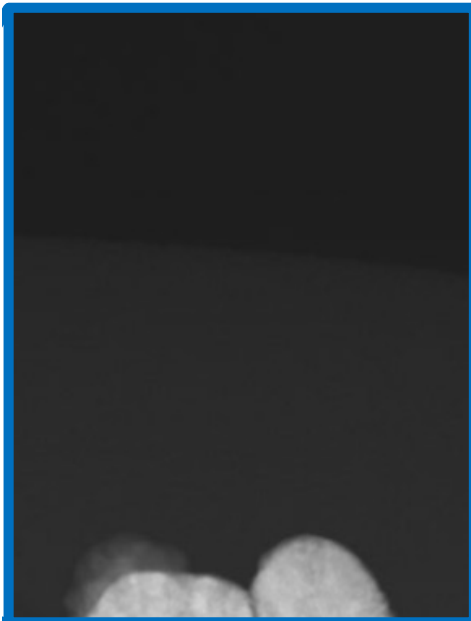
# TWICE Receiver Overview

- Three millimeter/submillimeter wave receivers on instrument
- Two receivers implemented in recently available 25 nm InP HEMT
  - 660-680 GHz dual direct detection receivers (two orthogonal polarizations)
  - 230-390 GHz broadband receiver
- This talk provides an overview of progress of these two receivers



## Scaling enables significantly enhanced performance

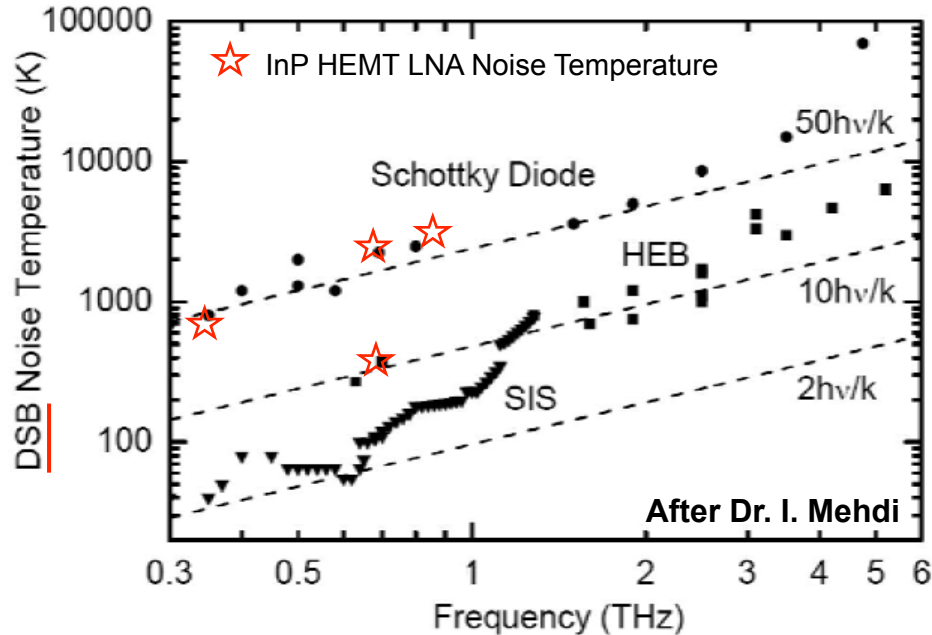
- 25 nm gatelength
- $f_{\text{max}}$ : 1.5 THz
- $f_{\text{T}}$ : 0.61 THz





# Submillimeter LNA's

## Mixer DSB Noise Performance



- InP HEMT LNA sensitivity approaches that of DSB mixers.
- InP HEMT LNA is superior to that of mixers operated in SSB mode.
- This extends to cryogenic operation.

## 670 GHz Comparison

	Ambient Temperature [K]	Noise Figure [dB]	Noise Temperature [K]
HEMT	270	9.6	2355
	25	3.8	400
GaAs Schottky	270	9.4 DSB (12.4 SSB*)	2236 DSB (4750 SSB*)
HEB	Cryo	2.7 DSB (5.7 SSB*)	250 DSB (788 SSB*)
SIS	4	1.3 DSB (4.3 SSB*)	100 DSB (491 SSB*)

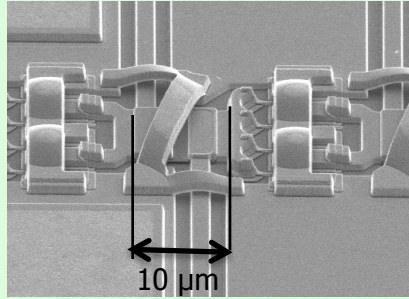
## 850 GHz Comparison

	Ambient Temperature [K]	Noise Figure [dB]	Noise Temperature [K]
HEMT	270	12	3361
GaAs Schottky	270	9.8 DSB (12.8 SSB*)	DSB 2500 (5236 SSB*)

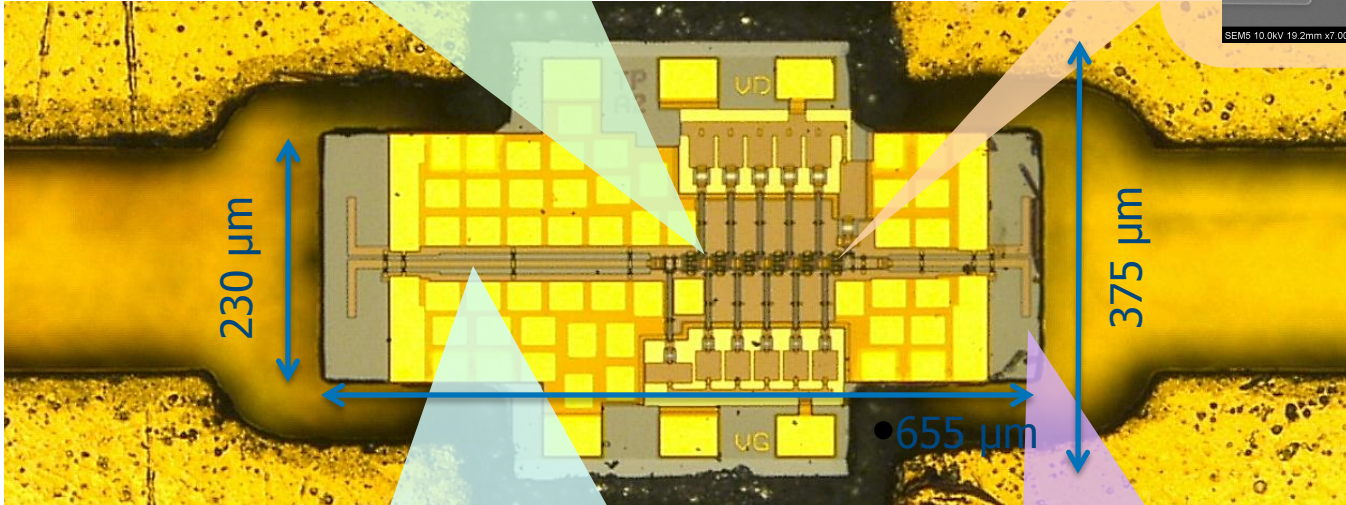
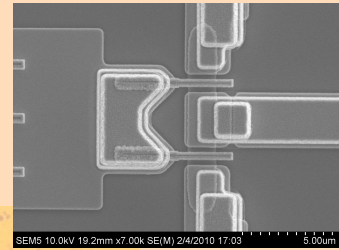
\*Performance estimated from plot. SSB is calculated from DSB by adding 3 dB

# THz Monolithic Integrated Circuit (TMIC)

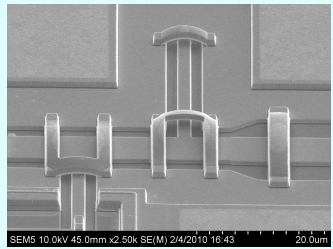
**Passive TMIC Technology:**  
High compaction.  
HEMT to HEMT spacing of 10  $\mu\text{m}$ .



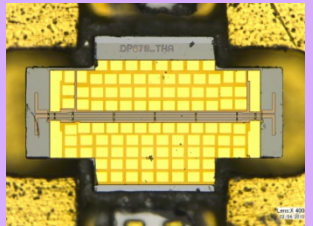
**Transistor Technology:**  
25 nm InP HEMT



**Coplanar Waveguide (CPW)**  
GND    Signal    GND  
InP

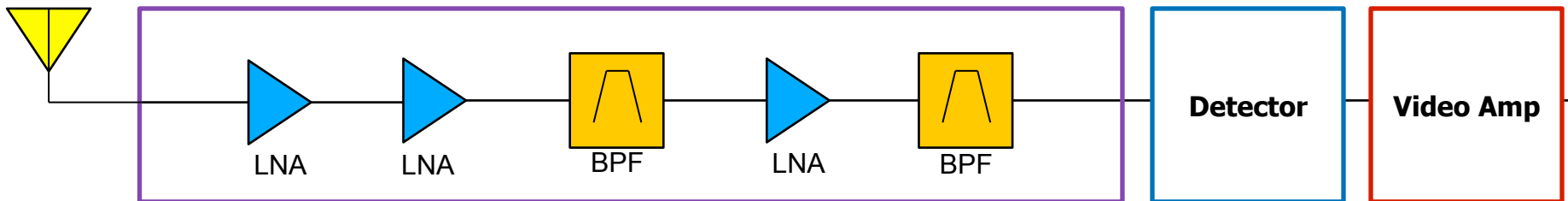
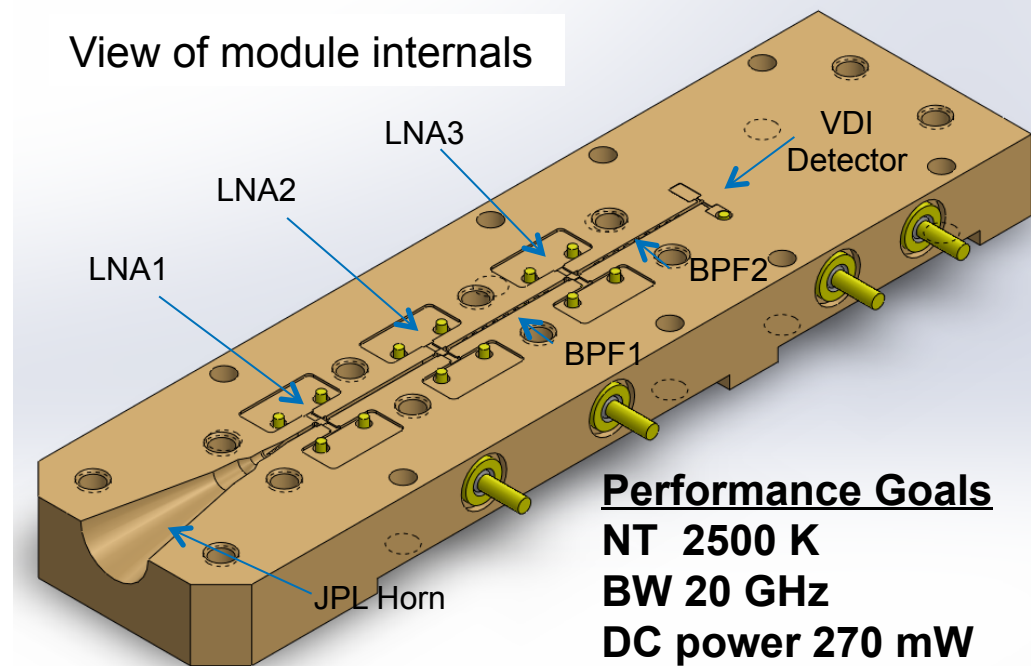


**Integration Challenges:**  
Need wide chip for circuit,  
but narrow for transition  
Cross-shaped chip



# 670 GHz Receiver Approach

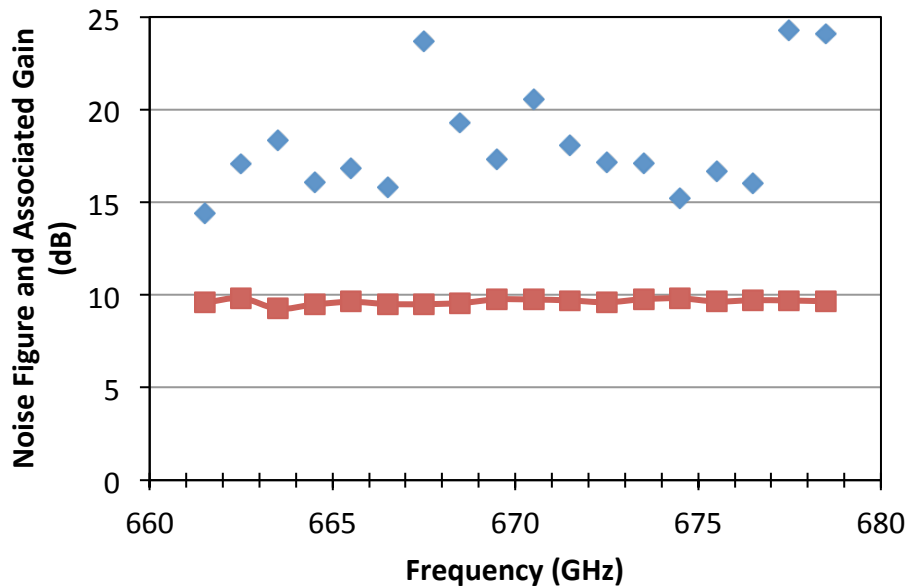
- Final receiver is an integrated, single-block 670 GHz Receiver
- Module includes:
  - Feedhorn (JPL)
  - LNA MMICs
  - Bandpass filters
  - Zero Bias Detector (VDI)
  - Video Circuitry
- Each functional block has been prototyped and evaluated
- Components have been evaluated together to evaluate integrated performance



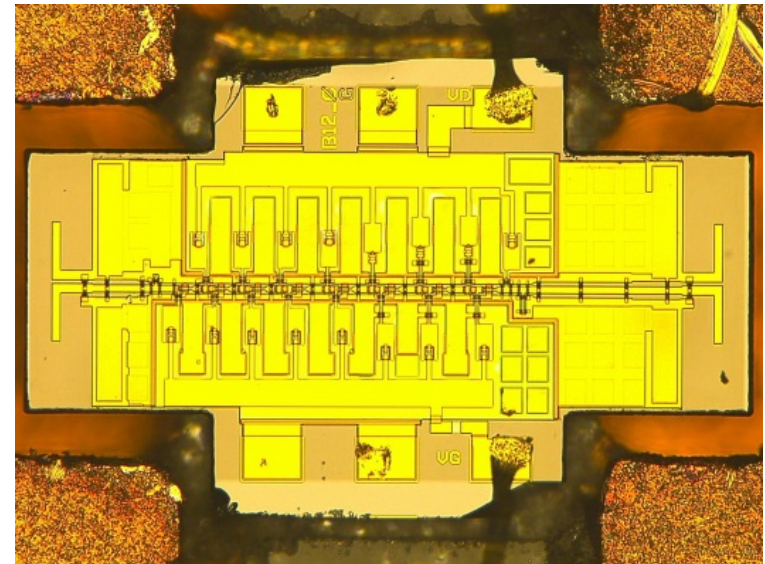
# 670 GHz LNA

- **670-GHz LNA:**
  - 8-stage, single-ended design
  - 2-Finger 12  $\mu\text{m}$  HEMTs
  - 655  $\mu\text{m}$  x 375  $\mu\text{m}$  die size

Packaged 670-GHz LNA Measured Gain and Noise Figure



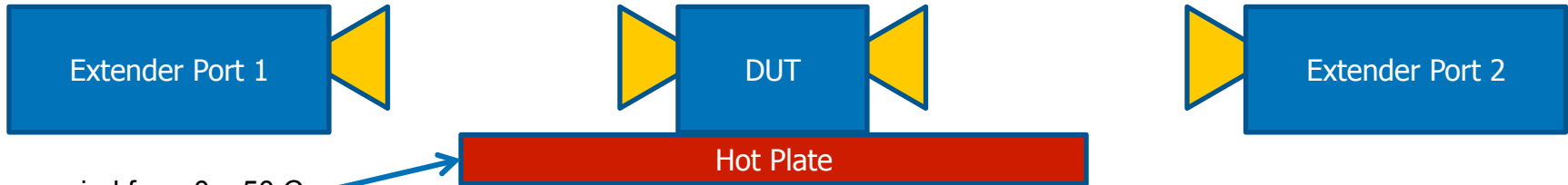
Packaged LNA TMIC



**9.6 dB Measured Noise Figure (NT=2400K)**

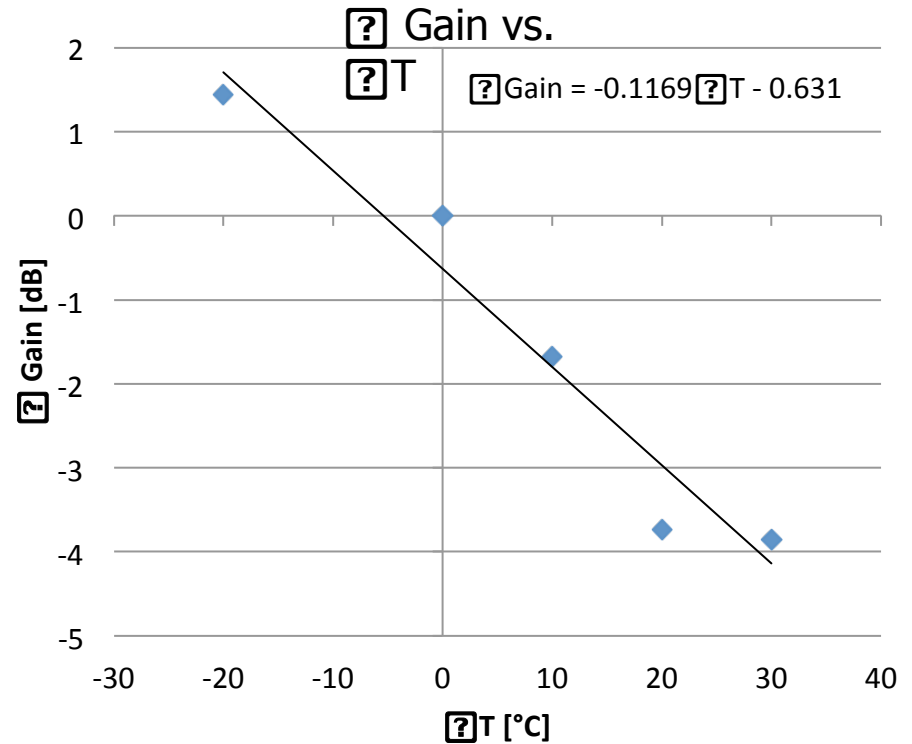
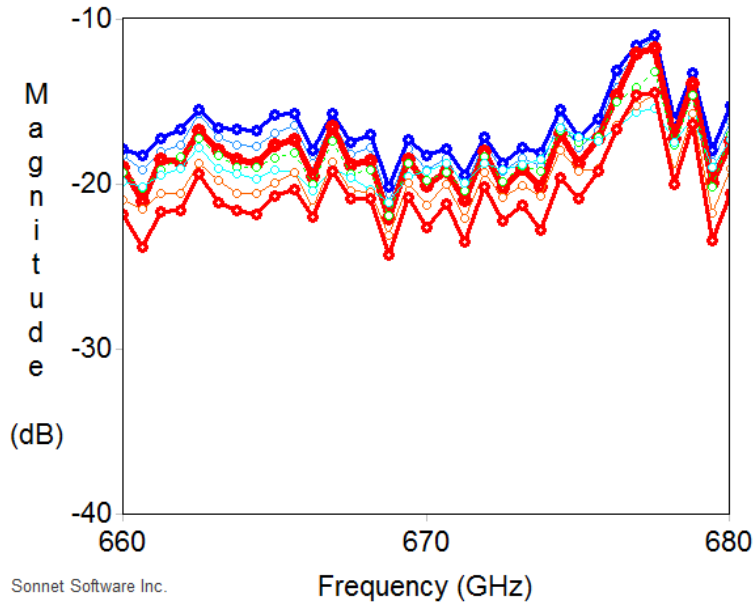


# 670 GHz LNA Gain vs. Temperature



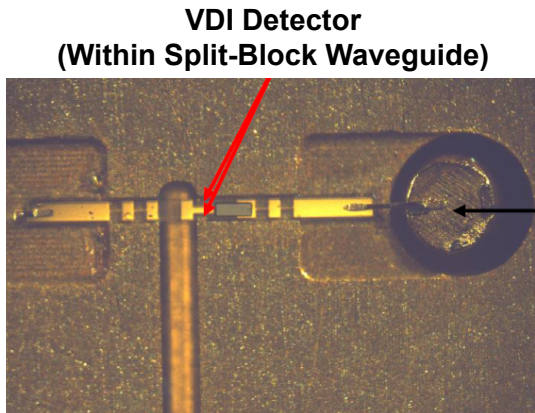
Temp varied from 0 - 50 C

## 670 GHz LNA over Temperature

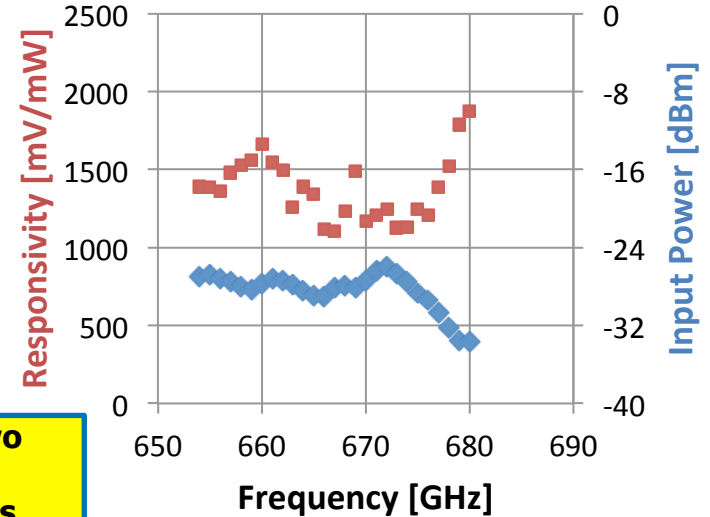


~0.01 dB/C per Device Measured

# Detector Responsivity Measurements

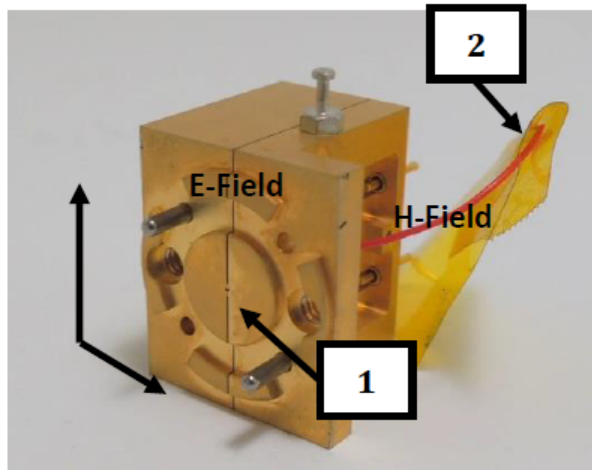


**Detector Measured Responsivity vs. Frequency**

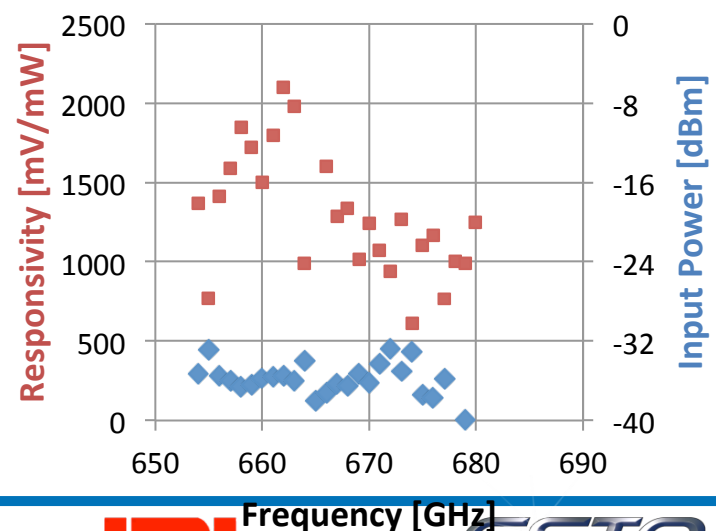


**Measured with two different input power levels**

**Fabricated and tested Detector Prototyping Module**



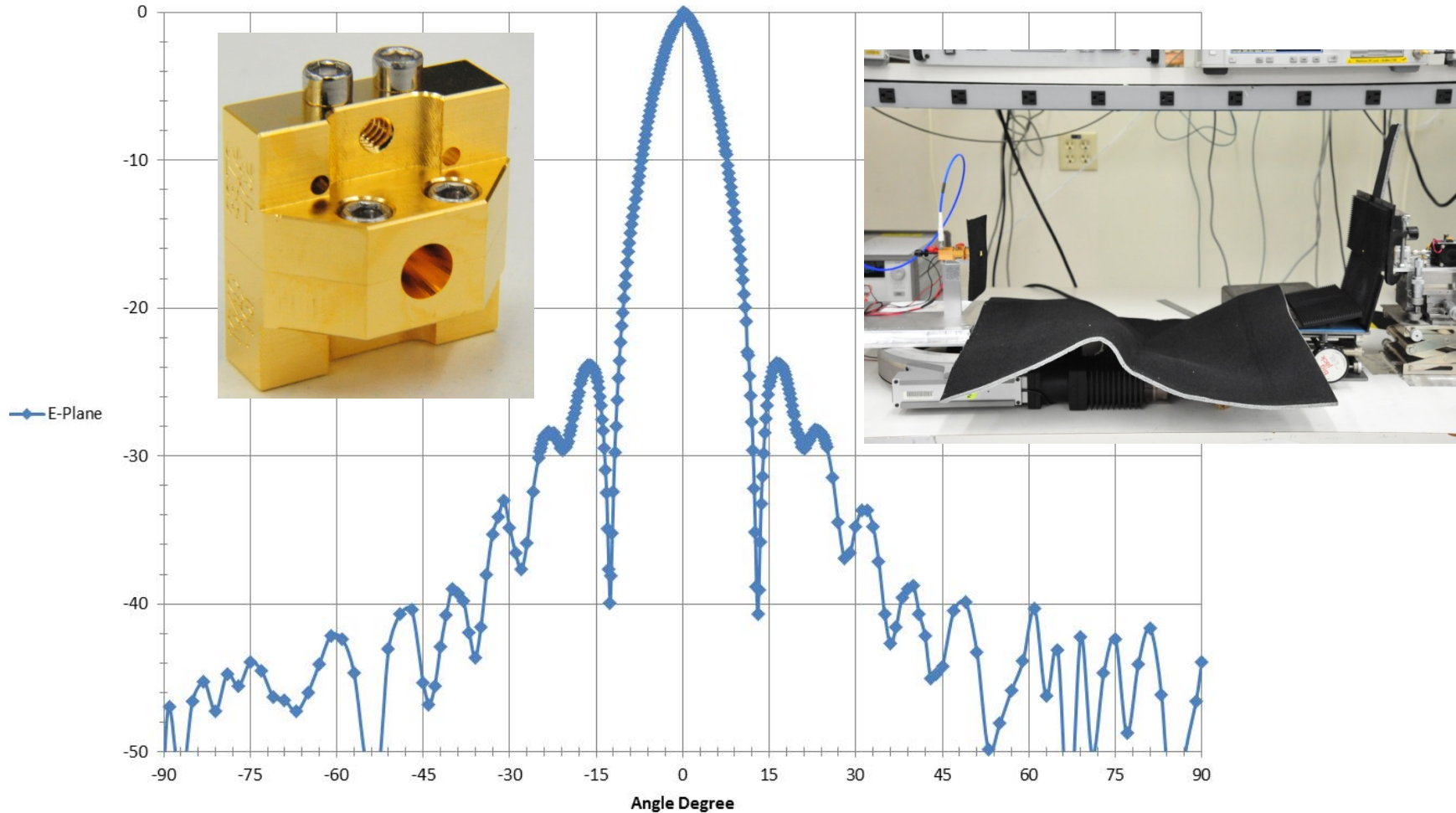
**Detector Measured Responsivity vs. Frequency**



# 670 GHz Radiation Pattern



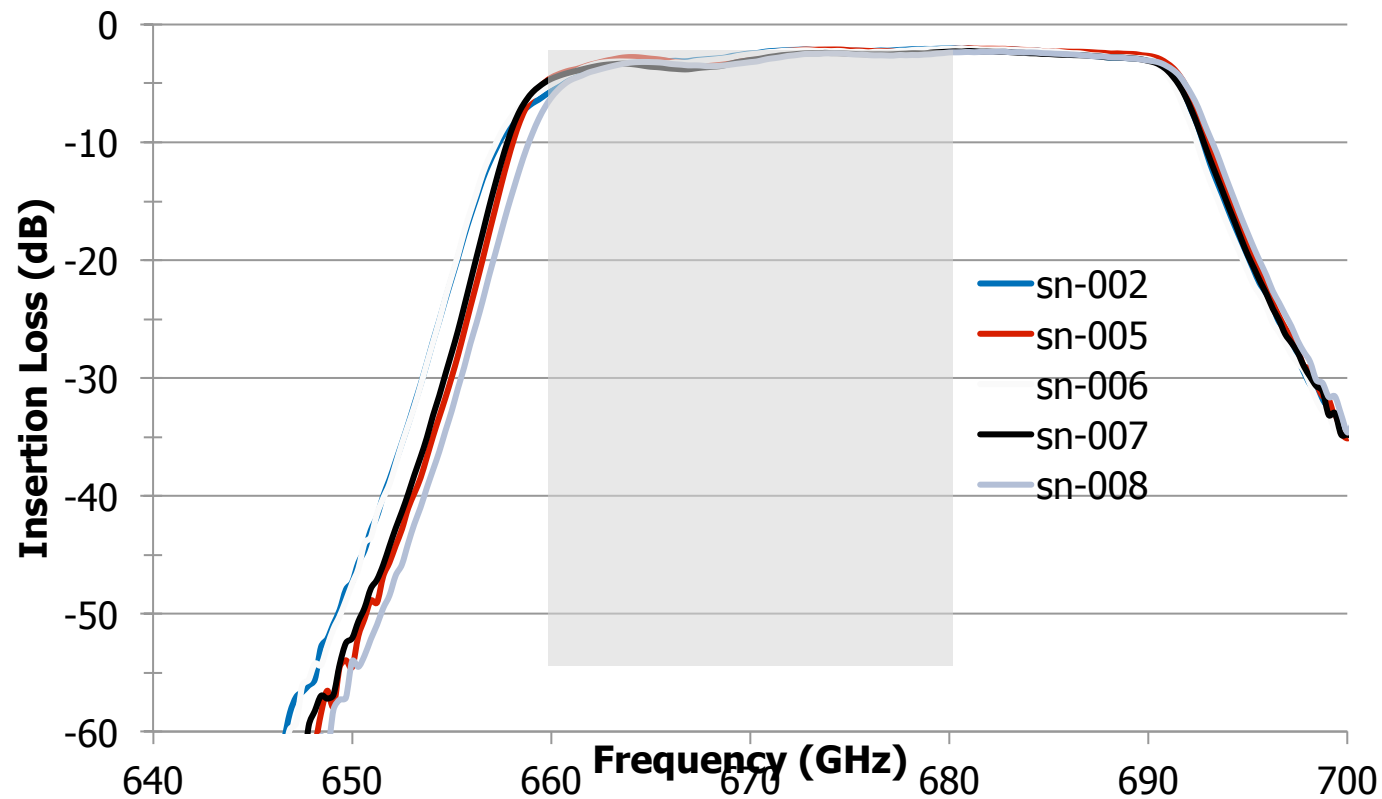
TWICE JPL WR1.5 Circular Horn SN:02, E-Plane



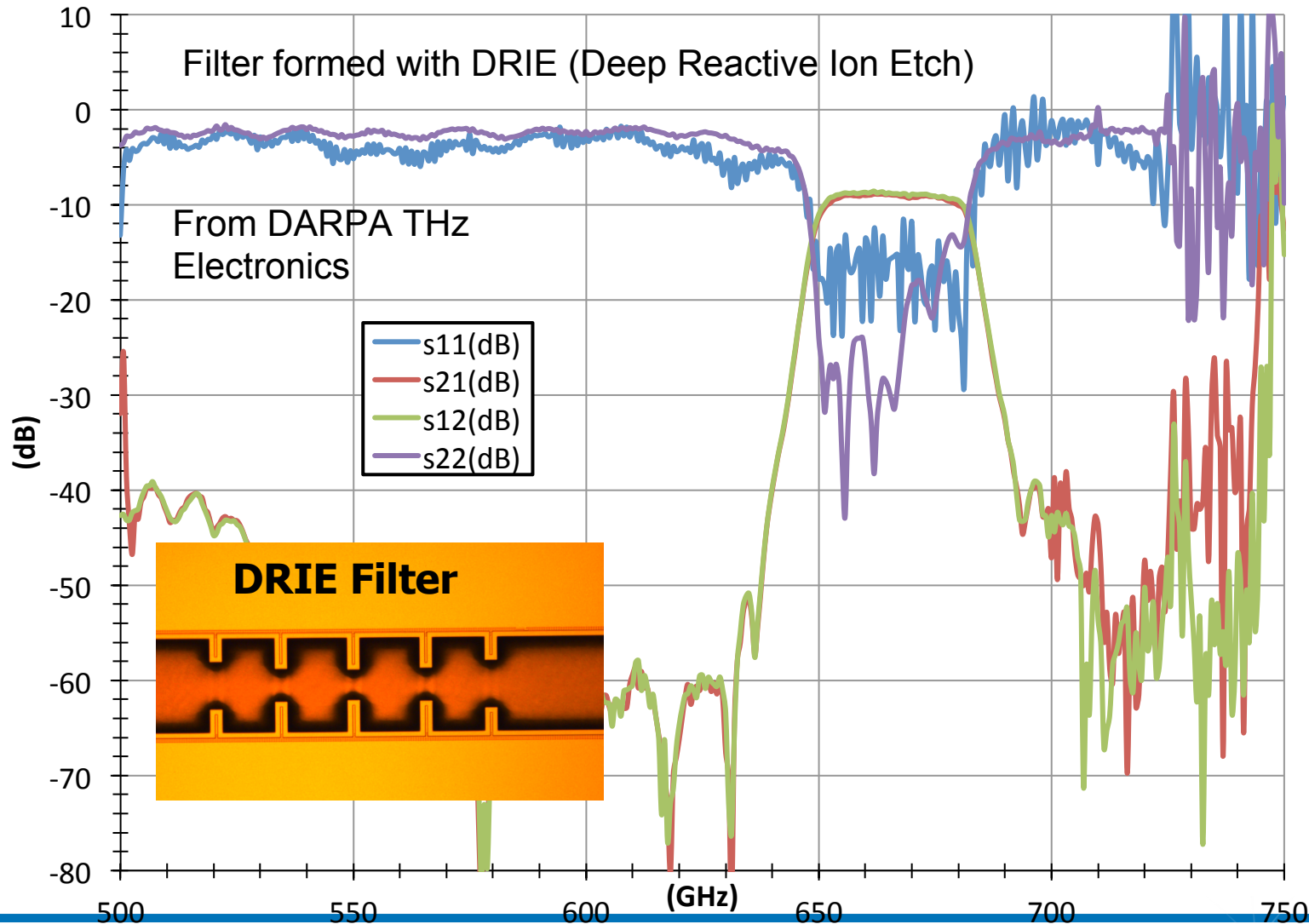
# Bandpass filter



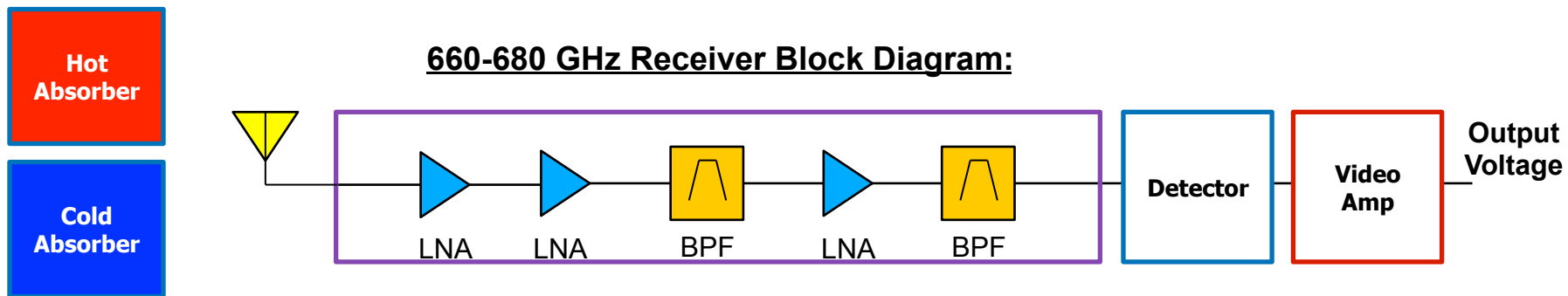
- CNC Machined Bandpass filter



# Other Filter Fabrication Techniques



# 670 GHz “Breadboard” Receiver Noise Temperature



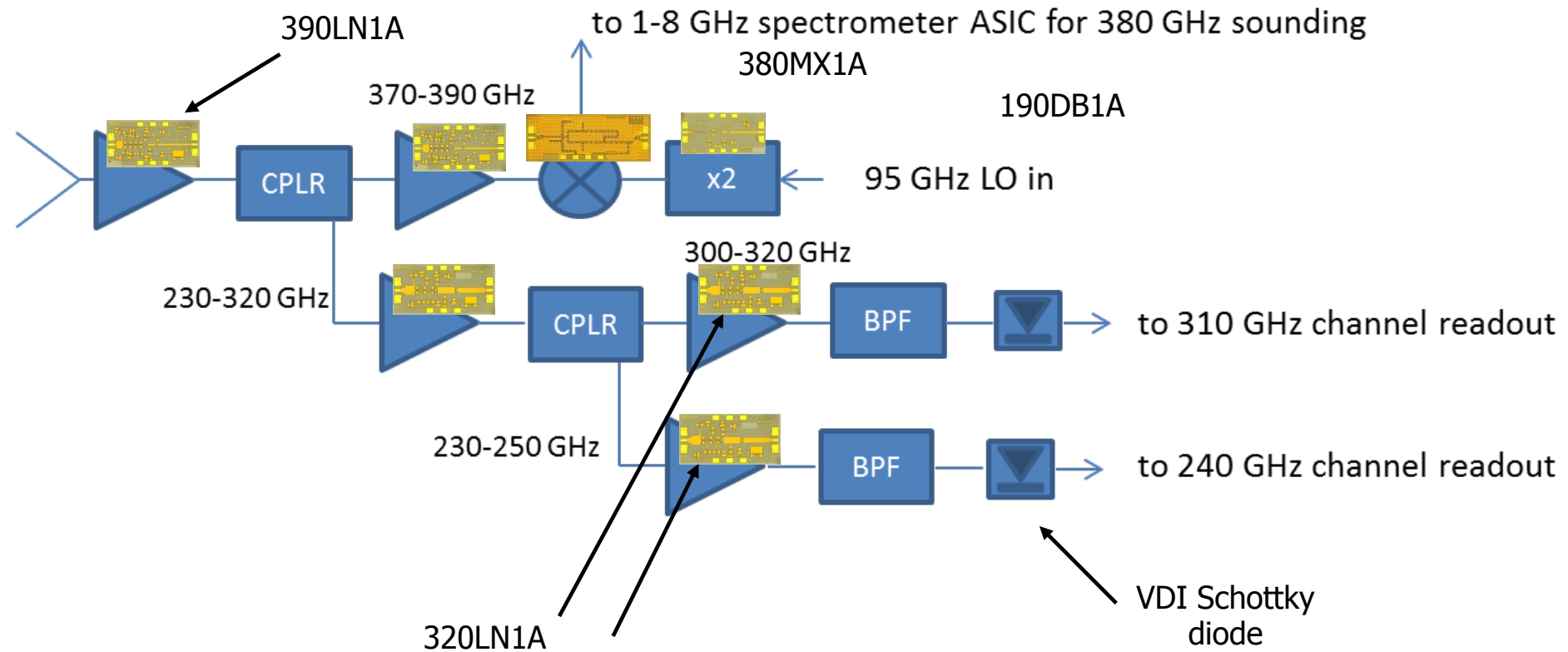
## Room Temperature 670 GHz Receiver Noise Temperature Characterization

Cold Load Temperature [K]	Hot Load Temperature [K]	Hot Load Output Voltage [mV]	Cold Load Output Voltage [mV]	Calculated Noise Temperature [K]
178	290.65	61.05	59.19	3406.81

# 230-390 GHz Receiver



- A single feedhorn integrated in the module will cover the 240, 310 GHz direct detection bands and the 380 GHz sounder band
- On-wafer test results for a full chip set

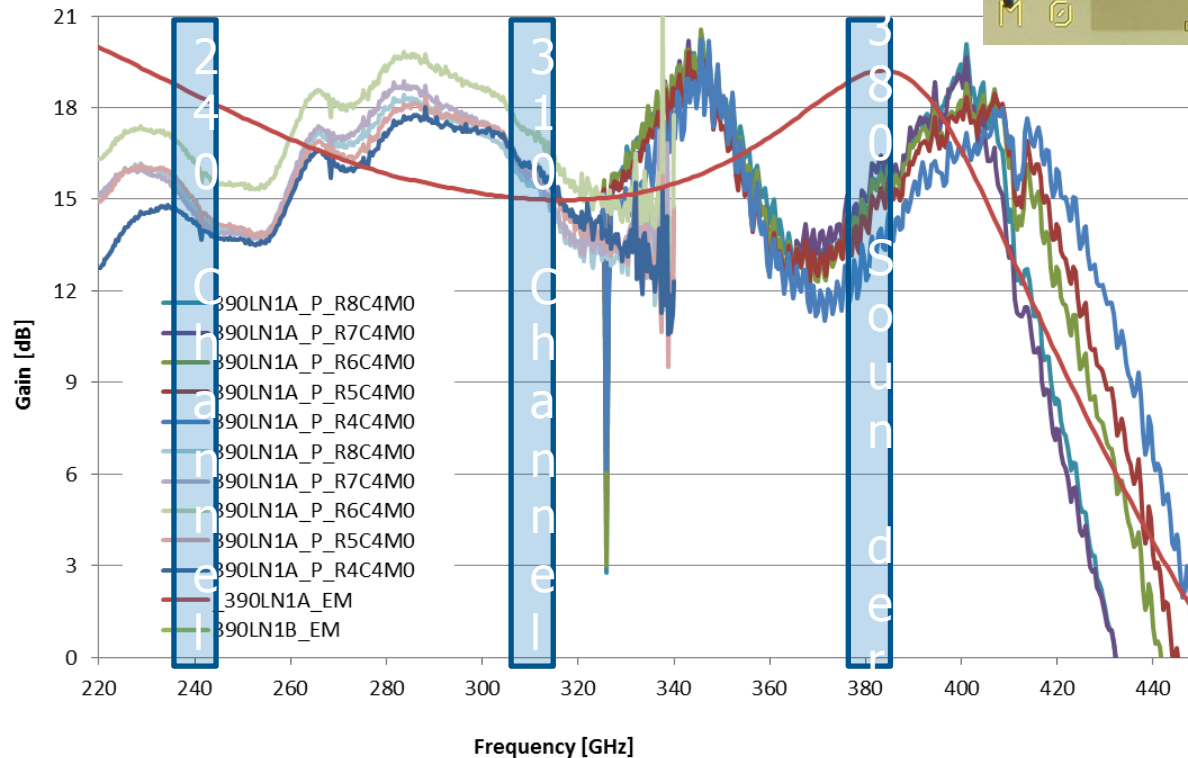
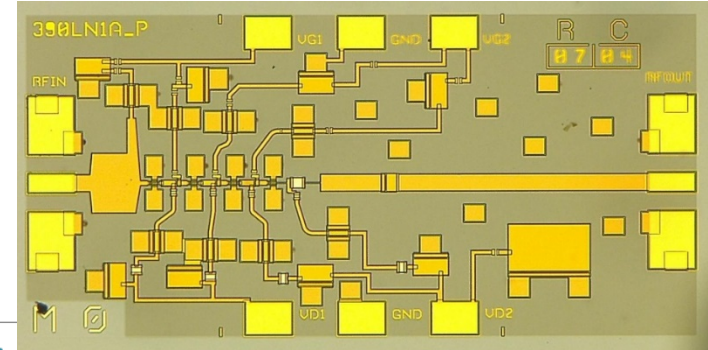


# 230-390 GHz Receiver



- 15-dB gain measured on-wafer
- Matches simulations
- Additional ripple from on-wafer calibration/ noise in measurement

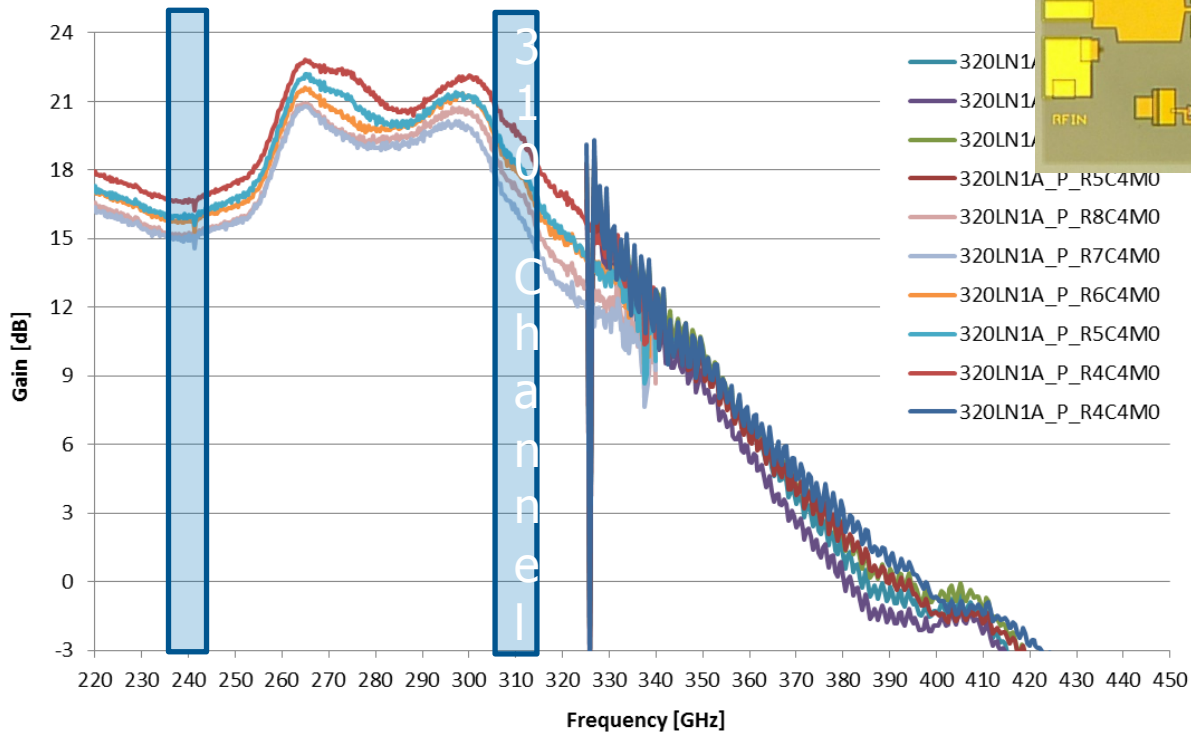
## Photograph of 230-390 GHz MMIC



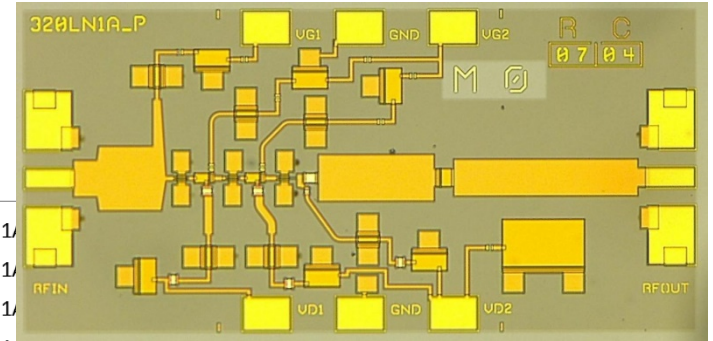


# 230-390 GHz Receiver

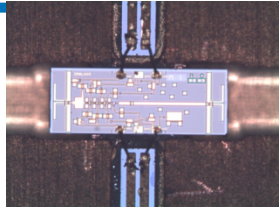
- 18-dB gain measured on-wafer
- Matches simulations



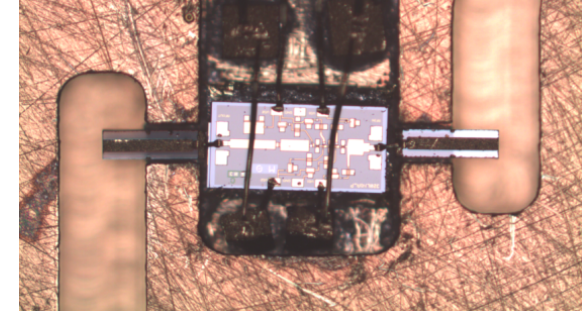
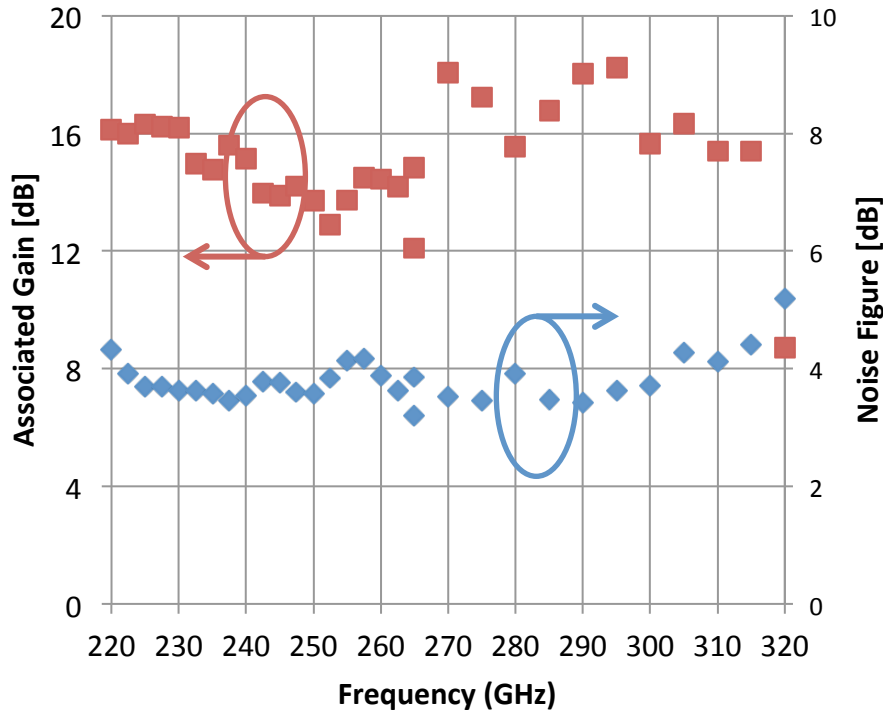
### Photograph of 230-320 GHz MMIC



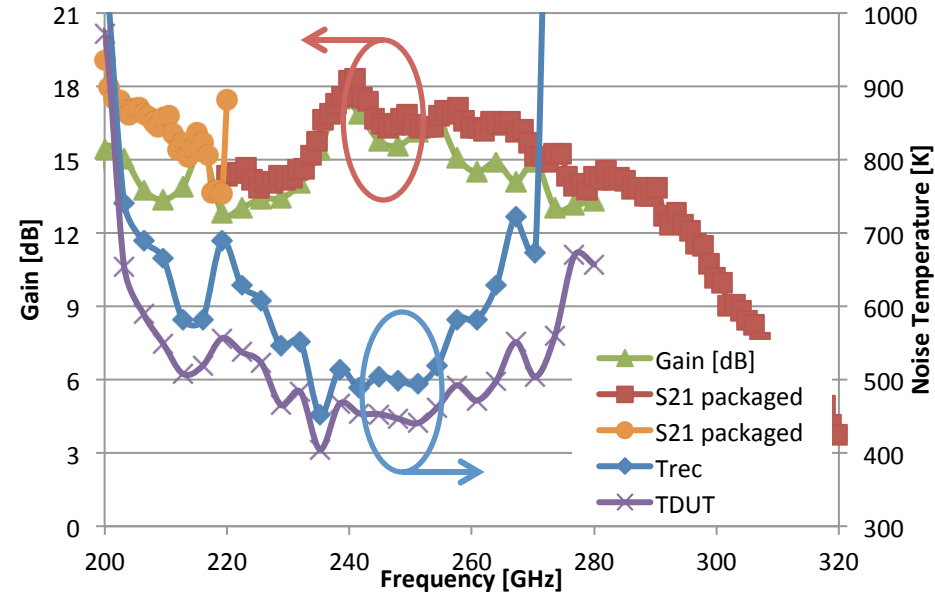
# 230-390 GHz Receiver: Packaging Approach



on chip transitions



wirebonded microstrip to WG transitions



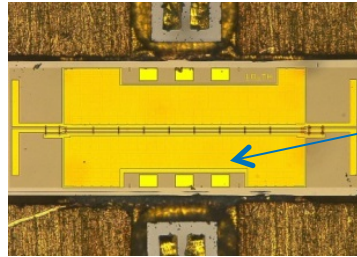
**3.8 dB Measured Noise Figure (NT 400K) @ 240 GHz**

**4.3 dB Measured Noise Figure (NT 500K) @ 310 GHz**

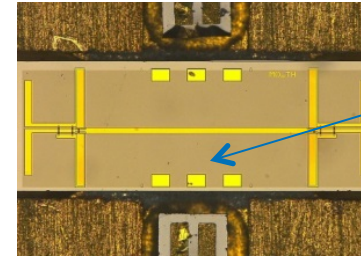
# 230-390 GHz Receiver



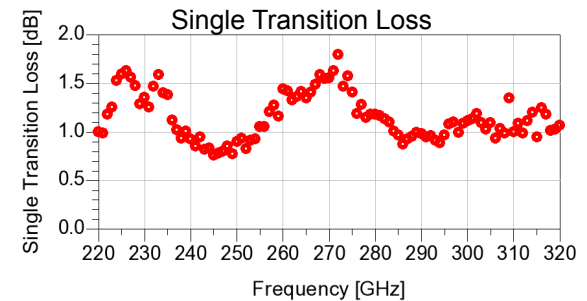
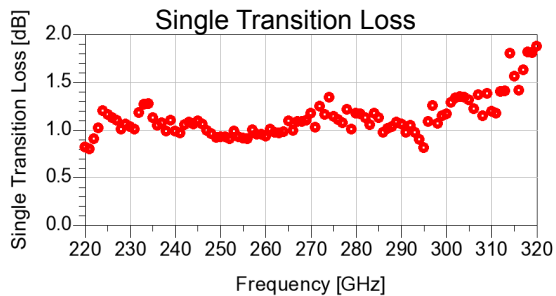
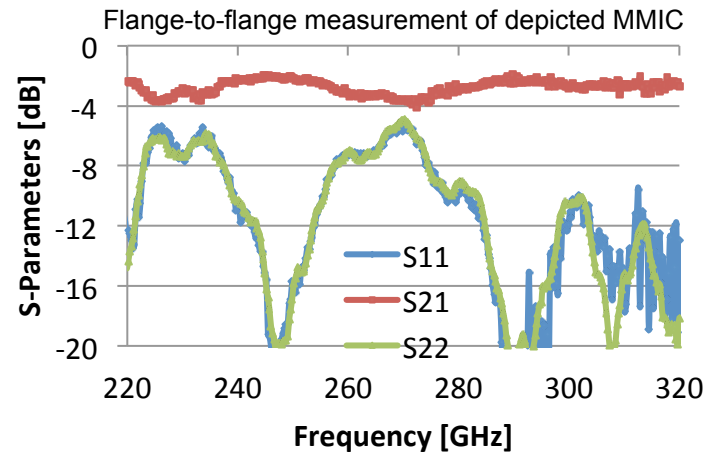
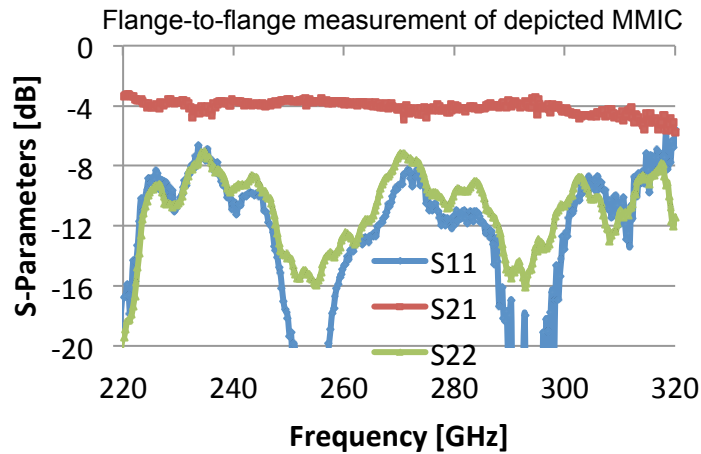
## 230-320 GHz Transition Loss Estimation



596  $\mu\text{m}$  CPW Line  
(Loss  $\sim 1.8$  dB)



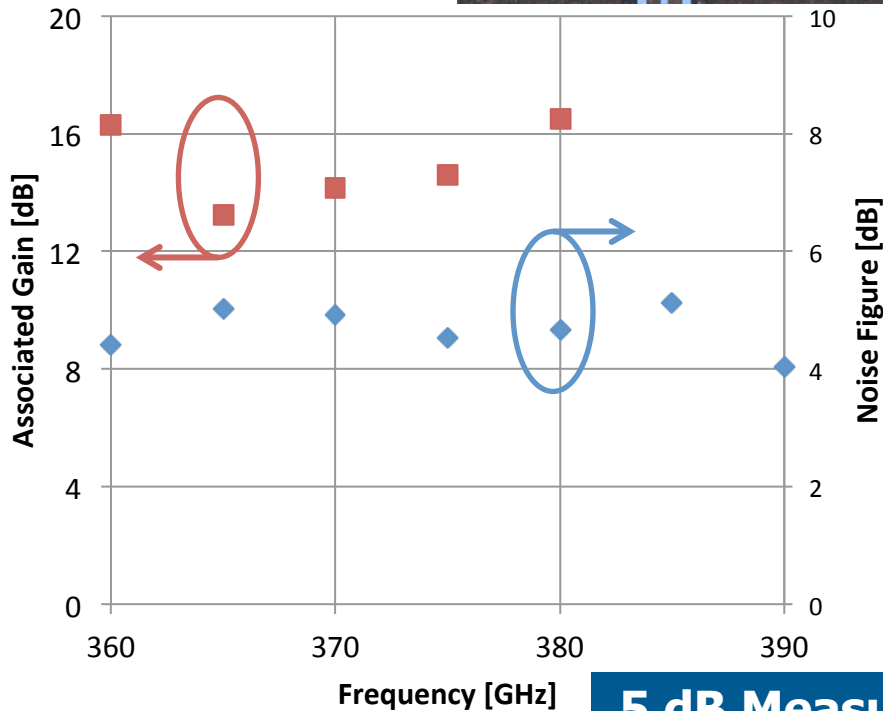
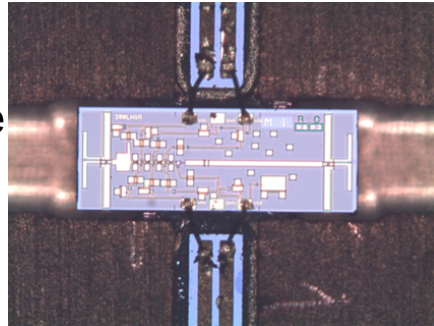
596  $\mu\text{m}$  MS Line  
(Loss  $\sim 0.5$  dB)



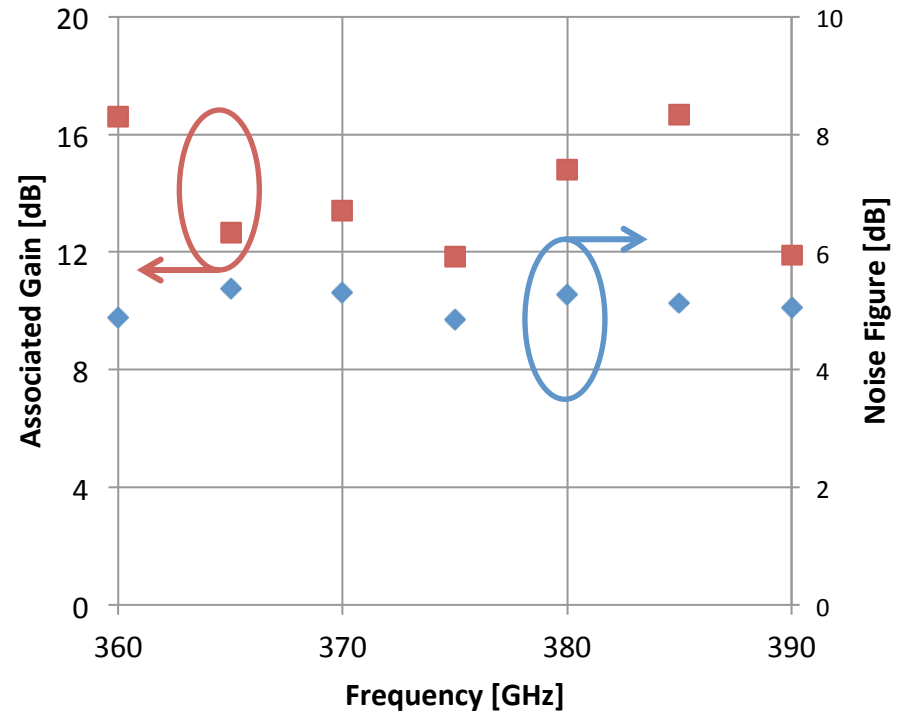
# 230-390 GHz Receiver



230–390 GHz LNA  
With Integrated  
narrowband waveguide  
transitions



360–390 GHz LNA  
Integrated waveguide  
transitions



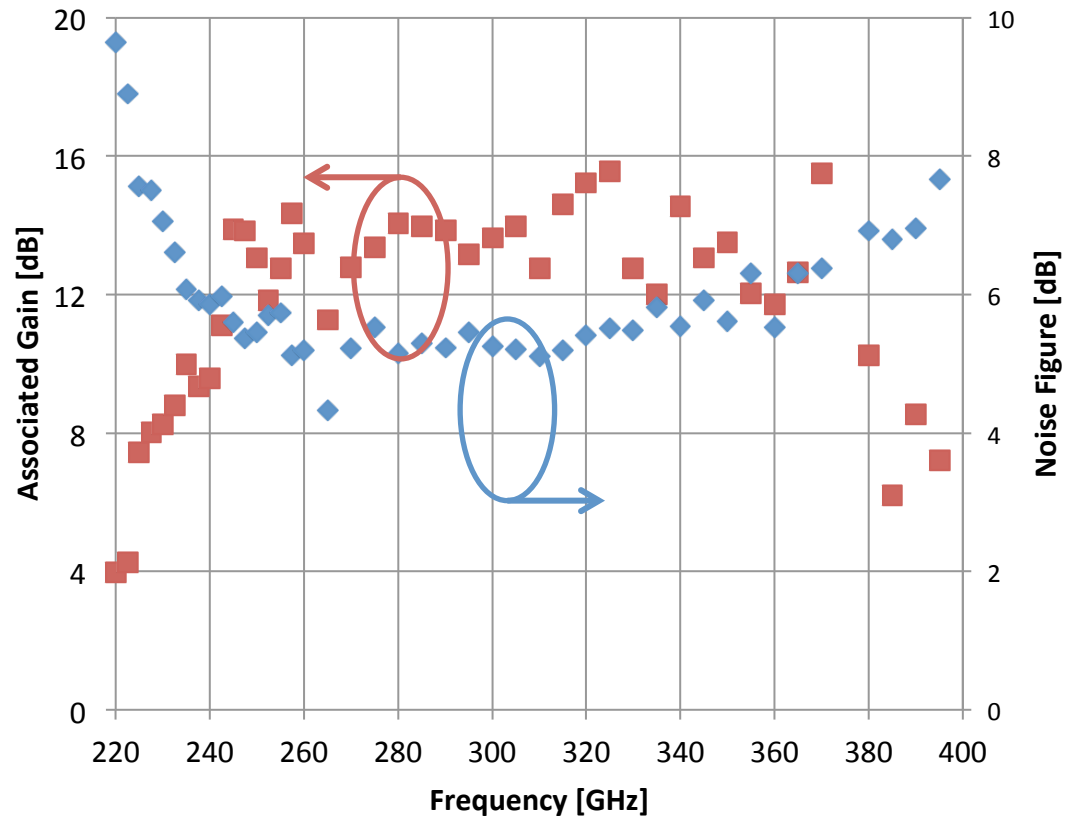
**5 dB Measured Noise Figure (NT=650K) @ 380 GHz**



# 230-390 GHz Receiver

## Currently:

230-390 GHz LNA with on-chip transition does not provide a significant advantage in receiver noise temperature compared to a diplexer followed by narrower band amplifiers



**6 dB Measured** Noise Figure (NT=900K) @ 240 GHz

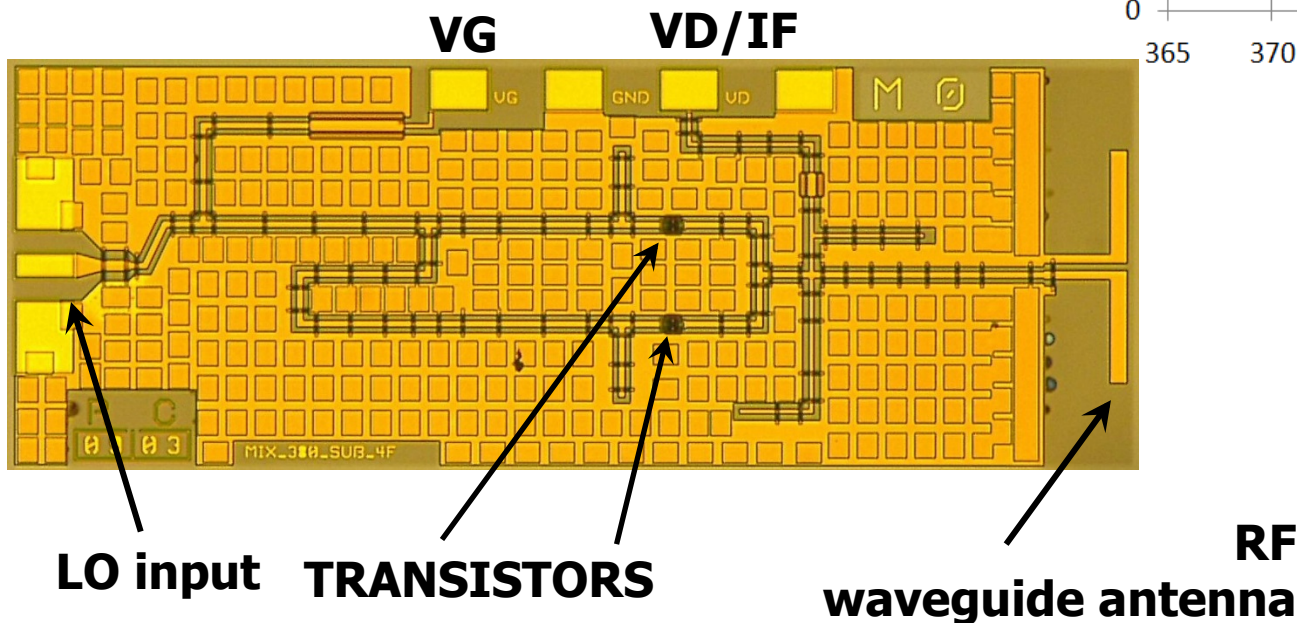
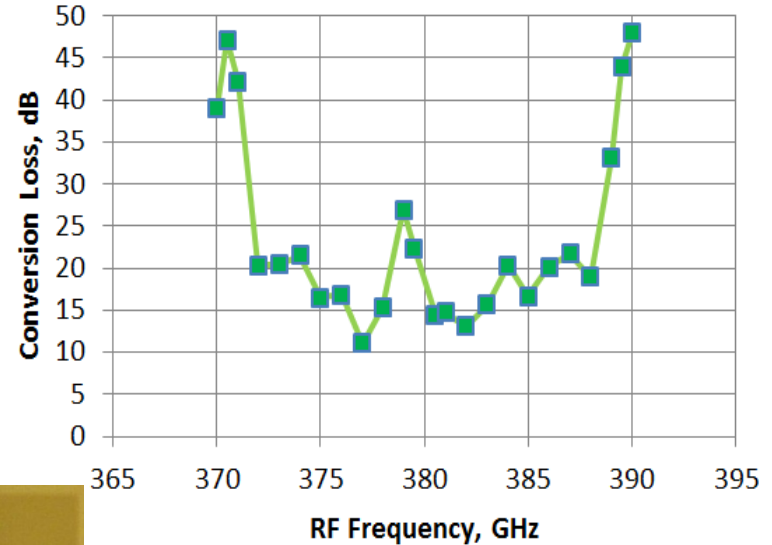
**5.5 dB Measured** Noise Figure (NT=650K) @ 310 GHz

**7 dB Measured** Noise Figure (NT=1200K) @ 380 GHz

# 230-390 GHz Receiver

## 380 GHz second harmonic mixer

- Broadband, 370 to 390 GHz
- Conversion loss  $\sim 15$  dB for 6 dBm LO power
- Balanced design uses 2 transistors pumped  $180^\circ$  out of phase
- Chip size  $375 \times 1000 \mu\text{m}^2$

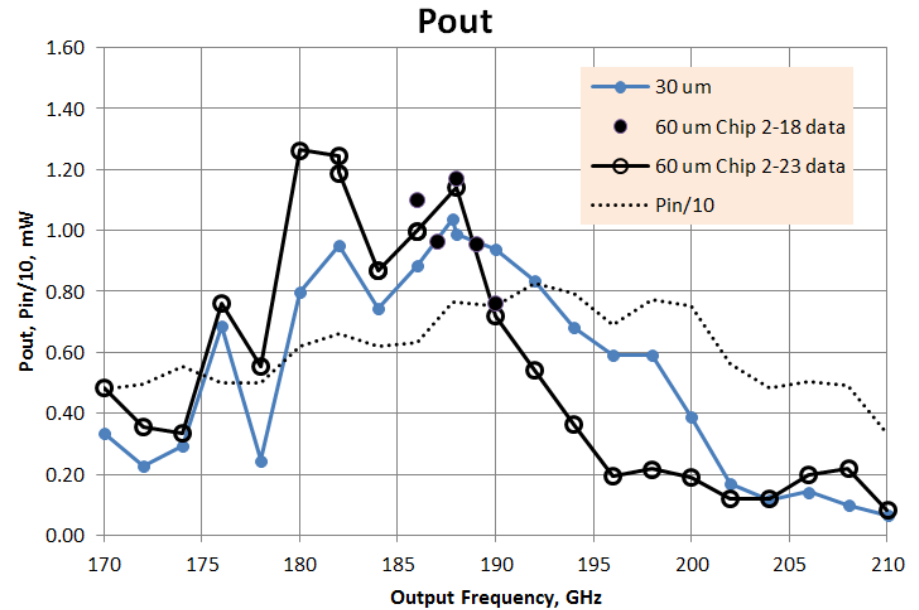
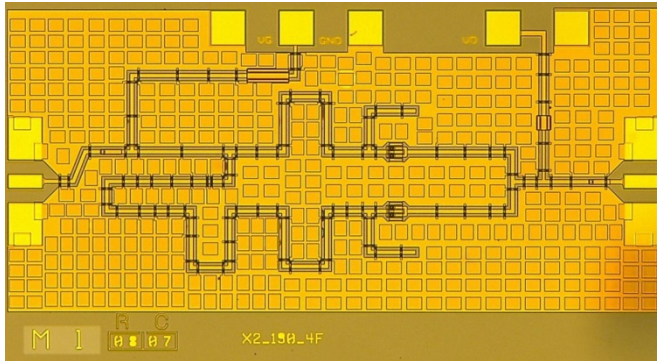


# 230-390 GHz Receiver



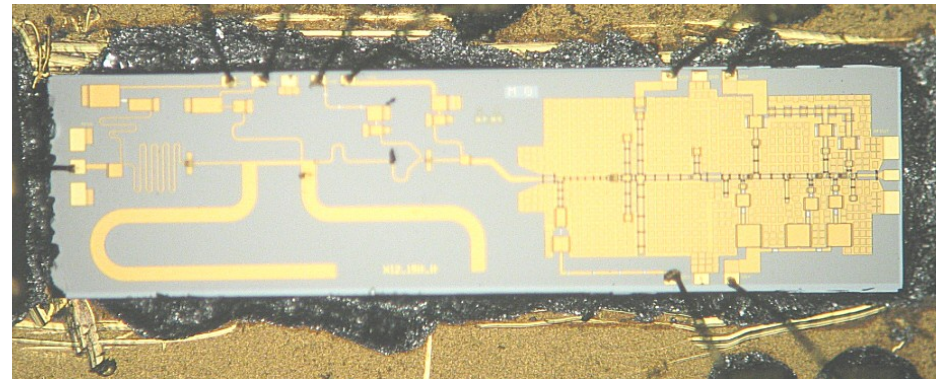
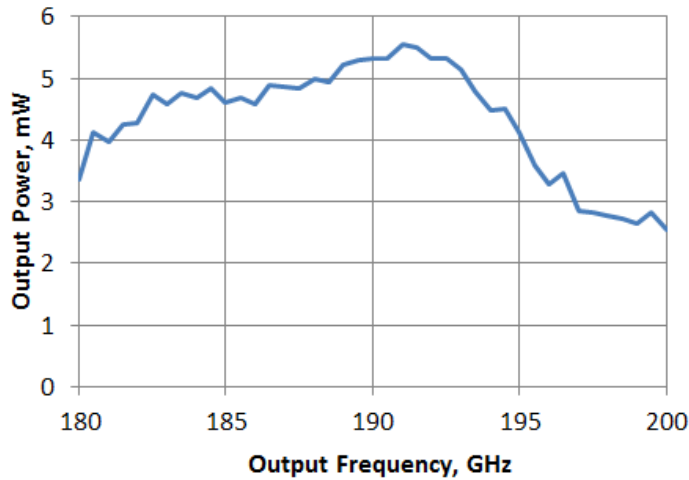
190 GHz frequency multipliers

x2



Frequency Sweep, -1.5 dBm in

x12



# Conclusion



- Significant progress has been made in the new TWICE receivers
  - “Breadboard” demonstration of 670 GHz direct detect receiver complete
  - 230-390 GHz MMIC components demonstrated
- Currently completing 2<sup>nd</sup> MMIC design iteration
- Integrated Receiver housing on order
- Prototype will be assembled and tested by August



***THE VALUE OF PERFORMANCE.***

***NORTHROP GRUMMAN***

